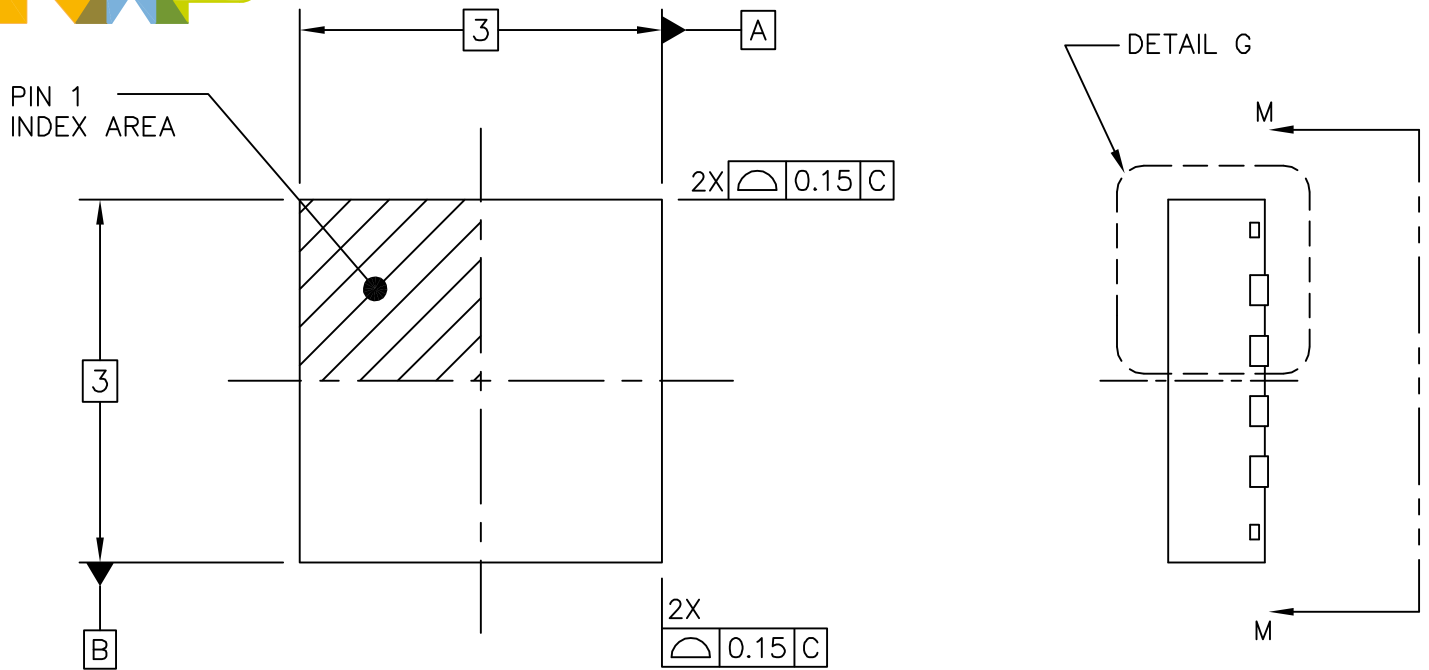

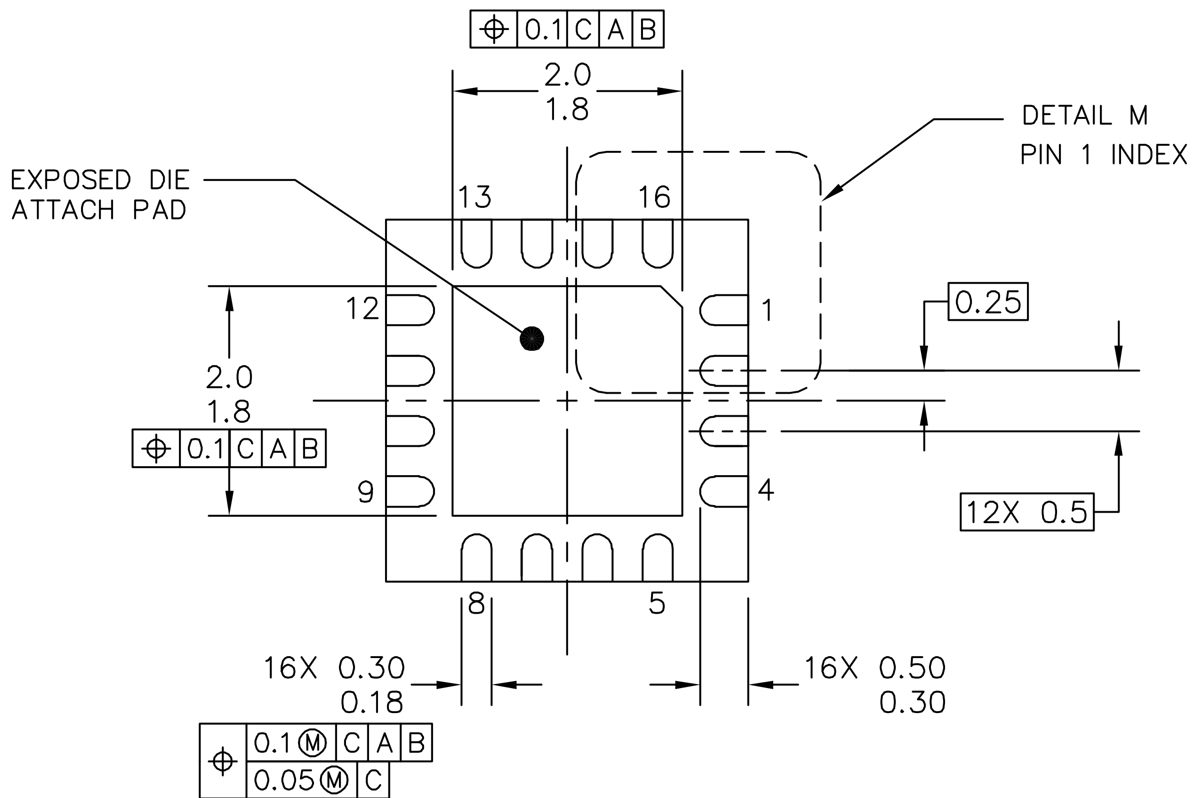

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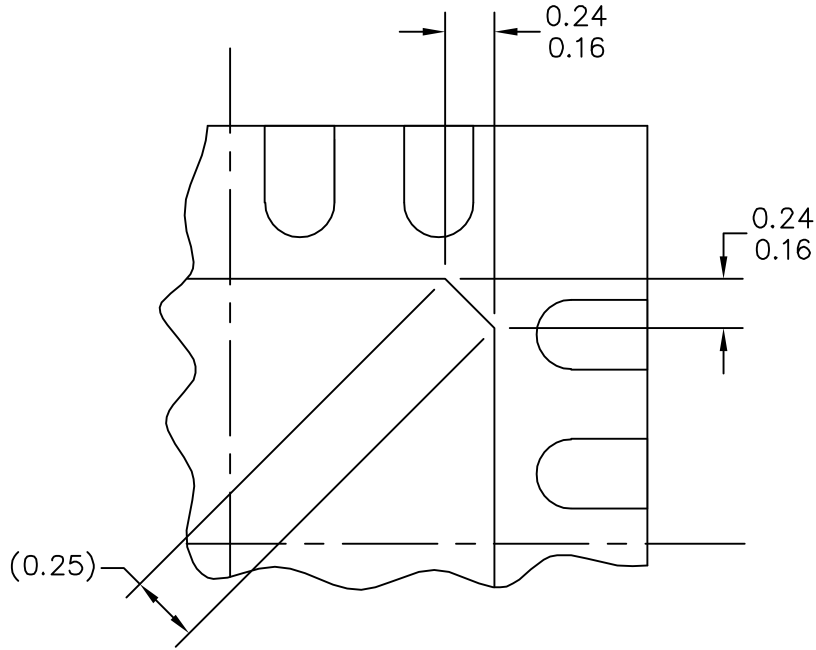
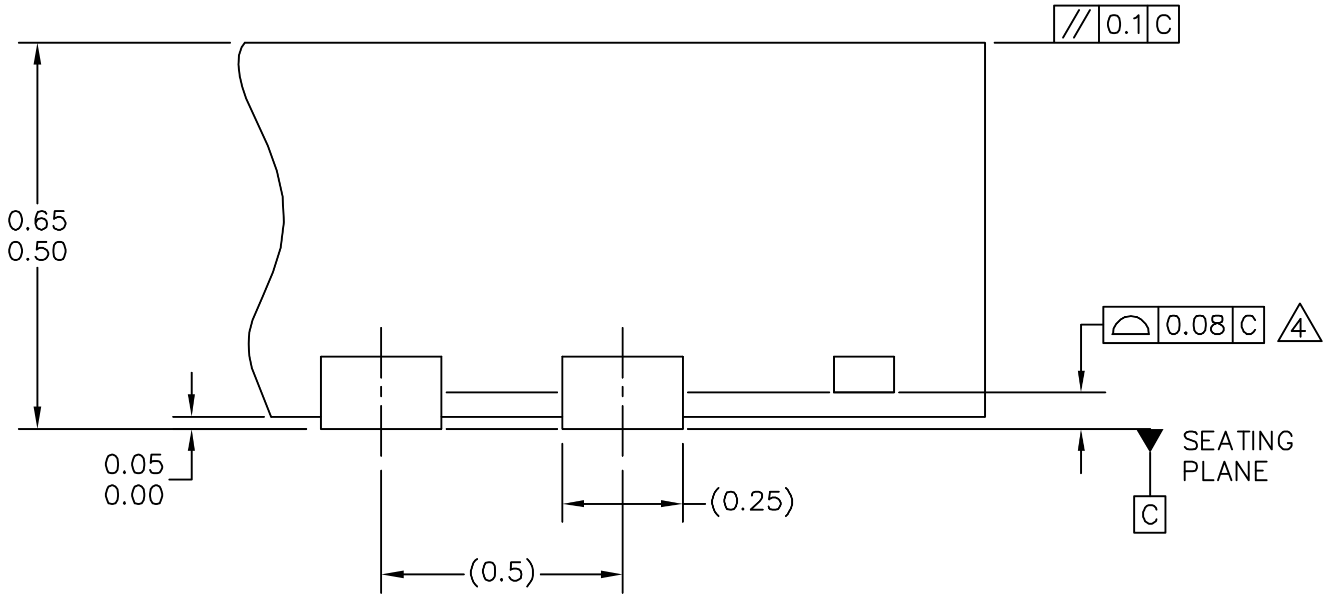
TITLE: THERMALLY ENHANCED ULTRA THIN QUAD FLAT NON—LEADED PACKAGE (UQFN), 16 TERMINAL, 0.5 PITCH, 3 X 3 X 0.65 PKG, TYPE—E LEAD	DOCUMENT NO: 98ASA00110D	REV: A
	STANDARD: NON—JEDEC	
	SOT1581—1	05 JAN 2016



DETAIL M

PIN 1 BACKSIDE IDENTIFIER



DETAIL G

VIEW ROTATED 90° CW

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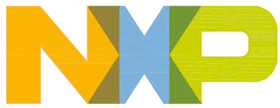
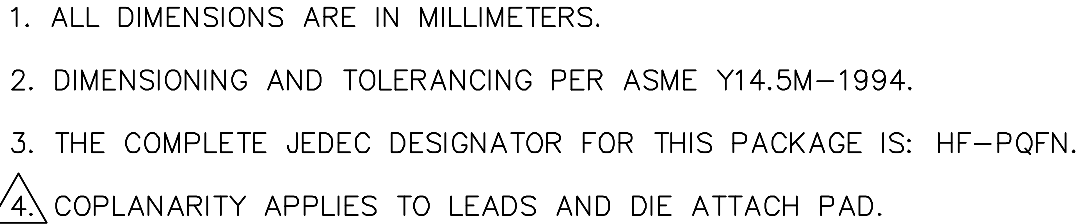
	SOT1581–1	05 JAN 2016



NOTES:



1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFN.
4. (△) COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

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